

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claim 1. (canceled).

Claim 2. (previously presented): The semiconductor device ~~according to claim 1~~
comprising:
an organic insulating film having an opening,
wherein said organic insulating film has an insulated modified portion in a side of said
opening, and
said modified portion includes nitrogen atoms and carbon atoms,
wherein said modified portion further comprises fluorine atoms, and
a concentration of said fluorine atoms in said modified portion is lower than a
concentration of said nitrogen atoms.

Claim 3. (original): The semiconductor device according to claim 2, further
comprising:
a metal conductor whose main component is copper, formed in said opening.

Claim 4. (previously presented): The semiconductor device according to claim 3,
wherein said metal conductor is in direct contact with said modified portion.

Claim 5-18 (canceled).

Claim 19. (previously presented): The semiconductor device according to claim 4, wherein the metal conductor comprises a barrier film whose main component is tantalum.

Claim 20. (previously presented): The semiconductor device according to claim 19, wherein the barrier film is in direct contact with the modified portion.